

EV549570797

Sheet 1 of 2

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTORNEY DOCKET
NO. MI22-2308SERIAL NO.
10/615,051

LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)

APPLICANT: Brian A. Vaartstra

FILING DATE
7/7/2003GROUP ART UNIT
2823

U.S. PATENT DOCUMENTS

*Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
Bu	AA	6,013,583	1/11/2000	Ajmera et al.			
Bu	AB	2001/0041250 A1	11/2001	Haukka et al.			
Bu	AC	2002/0000195 A1	1/2002	Kao et al.			
	AD	2003/00129826 A1	7/10/2003	Werkhoven et al.			
Bu	AE	2003/0032281 A1	2/13/2003	Werkhoven et al.			
Bu	AF	5,770,469	6/1998	Uram et al.			
Bu	AG	2004/0266153 A1	12/30/2004	Yongjun Jeff Hu			
	AH						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
Bu	AI	EP 0817251 A	1/1998	EPO				
	AJ							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

Bu	AK	PCT/US2004/021156; Filed 6/30/2004; Search Report.
Bu	AL	PCT/US2004/021156; Filed 6/30/2004; Written Opinion Issued on 1/18/2005; 6 pps.
EXAMINER Brook Kebede		DATE CONSIDERED 7/5/2005

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. MI22-2308	SERIAL NO. 10/615,051
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT: Brian A. Vaartstra	
		FILING DATE 07/07/2003	GROUP 2823

U.S. PATENT DOCUMENTS							
Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
	AC						
	AD						
	AE						

FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AF							
	AG							
	AH							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)			
BK	AI		Chen et al., <i>Excimer Laser-Induced Ti Silicidation to Eliminate the Fine-Line Effect for Integrated Circuitry</i>
			<i>Device Fabrication</i> , 149 JOURNAL OF ELECTROCHEMICAL SOCIETY, No. 11, pp. G609-G612 (2002).
BK	AJ		Nishiyama et al., <i>Agglomeration Resistant Self-Aligned Silicide Process Using N₂ Implantation into TiSi₂</i>
			36 JPN. J. APPL. PHYS., Part 1, No. 6A, pp. 3639-3643 (June 1997).
BK	AK		Wolf, <i>Chapter 13: Polycides and Salicides of TiSix, CoSi₂, and NiSi</i> , SILICON PROCESSING FOR THE VLSI ERA,
			Vol. IV, pp. 603-604 (pre-2003).
EXAMINER		DATE CONSIDERED	
Brook Kehede		7/5/2005	
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			